

PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1
 Stylesheet Version v1.2

EPAS ID: PAT4651260

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
YOSHIMITSU YANAGAWA	07/25/2017
MASAHIRO MATSUMOTO	07/25/2017
HIROSHI NAKANO	07/25/2017
AKIRA KOTABE	07/25/2017
SATOSHI ASANO	07/25/2017
RECEIVING PARTY DATA	
Name:	HITACHI AUTOMOTIVE SYSTEMS, LTD.
Street Address:	2520, TAKABA
City:	HITACHINAKA-SHI, IBARAKI
State/Country:	JAPAN
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	15568340
CORRESPONDENCE DATA	
Fax Number:	
<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i>	
Phone:	202-672-5300
Email:	ipdocketing@foley.com, mboyce@foley.com
Correspondent Name:	FOLEY & LARDNER LLP
Address Line 1:	3000 K STREET N.W.
Address Line 2:	SUITE 600
Address Line 4:	WASHINGTON, D.C. 20007-5109
ATTORNEY DOCKET NUMBER:	096243-0175
NAME OF SUBMITTER:	MARY JO BOYCE
SIGNATURE:	/Mary Jo Boyce/
DATE SIGNED:	10/20/2017
Total Attachments: 1	
source=Assignment#page1.tif	

ASSIGNMENT
(譲渡証)

As a below named inventor, I hereby declare that:

IN CONSIDERATION of the sum of One Dollar (\$1.00) or the equivalent thereof, and other good and valuable consideration paid to me by HITACHI AUTOMOTIVE SYSTEMS, LTD., a corporation organized under the laws of Japan, located at 2520, Takaba, Hitachinaka-shi, Ibaraki, Japan, receipt of which is hereby acknowledged I do hereby sell and assign to said HITACHI AUTOMOTIVE SYSTEMS, LTD., its successors and assigns, all my right, title and interest, in and for the United States of America, in and to

SEMICONDUCTOR CHIP HAVING ON-CHIP NOISE PROTECTION CIRCUIT

invented by me (if only one is named below) or us (if plural inventors are named below) and described in the application for United States Letters Patent therefor, No.PCT/JP2016/059534 filed March 25, 2016, and all United States Letters Patent which may be granted therefor, and all divisions, continuations and extensions thereof, the said interest being the entire ownership of the said Letters Patent when granted, to be held and enjoyed by said HITACHI AUTOMOTIVE SYSTEMS, LTD., its successors, assigns or other legal representatives, to the full end of term for which said Letters Patent may be granted as fully and entirely as the same would have been held and enjoyed by me or us if this assignment and sale had not been made;

And I hereby agree to sign and execute any further documents or instruments which may be necessary, lawful, and proper in the prosecution of the above-named application or in the preparation and prosecution of any continuing, continuation-in-part, substitute, divisional, renewal, reviewed or reissue applications or in any amendment, extension, or interference proceedings, or otherwise to secure the title thereto in said assignee;

And I do hereby authorize and request the Commissioner of Patents to issue said Letters Patent to said HITACHI AUTOMOTIVE SYSTEMS, LTD.,

Signed on the date(s) indicated aside our signatures:

INVENTOR(S)
(発明者フルネームサイン)

Date Signed
(署名日)

1) Yoshimitsu Yanagawa Yoshimitsu YANAGAWA

Jul. 25, 2017

2) Masahiro Matsumoto Masahiro MATSUMOTO

7/25/2017

3) Hiroshi Nakano Hiroshi NAKANO

7/25/2017

4) Akira Kotabe Akira KOTABE

7/25/2017

5) Satoshi Asano Satoshi ASANO

7/25/2017

6) _____

7) _____

8) _____

9) _____

10) _____